

ABSTRACT OF THE DISCLOSURE

A semiconductor device comprises: a semiconductor chip;
an extension portion formed in contact with the side surfaces
so as to surround the semiconductor chip; an insulating film formed
5 on a surface of the extension portion and the semiconductor chip;
each of a plurality of wiring patterns electrically connected
to each electrode pad, respectively and extended from the
electrode pads to the surface of the extension portion; a sealing
portion formed such that a part of each of the wiring patterns
10 is exposed; and a plurality of external terminals provided over
the wiring patterns in a region including the upper side of the
extension portion.